

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:  
Hsu, et al.

Serial No.: 09/739,139

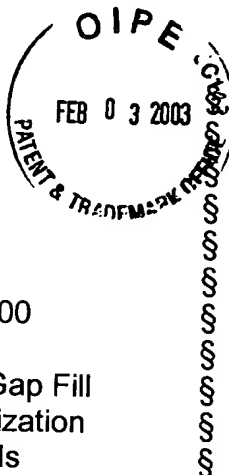
Confirmation No.: 4854

Filed: December 18, 2000

For: Integrated Multi-Step Gap Fill  
and All Feature Planarization  
for Conductive Materials

Assistant Commissioner for Patents  
Washington, D.C. 20231

Dear Sir:



Group Art Unit: 1763

Examiner: MacArthur, Sylvia

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CERTIFICATE OF MAILING 37 CFR 1.8	
I hereby certify that this correspondence is being deposited on January 27, 2003 with the United States Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231.	
Date 1/27/3	Signature <i>[Signature]</i>

RESPONSE TO OFFICE ACTION DATED AUGUST 28, 2002

In response to the Office Action dated August 28, 2002, having a shortened statutory period for response set to expire on November 28, 2002, please enter the following amendments and reconsider the claims pending in the application for reasons discussed below. A petition for a two-month extension of time to extend the statutory period for response to and including January 28, 2002, is attached to make this response timely. The commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782/AMAT/5614, for any fees, including extension of time fees and excess claim fees, required to make this response timely and acceptable to the Office.

IN THE TITLE:

Please change the title from "Integrated Multi-Step Gap Fill and All Feature Planarization for Conductive Materials" to --Method and Apparatus for Electro-Chemical Processing--.